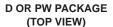
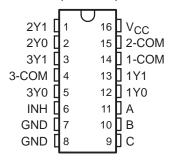
SCLS503C - MAY 2003 - REVISED MAY 2004

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 105°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree†
- 2-V to 5.5-V V_{CC} Operation
- Supports Mixed-Mode Voltage Operation on All Ports
- High On-Off Output-Voltage Ratio

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Low Crosstalk Between Switches
- Individual Switch Controls
- Extremely Low Input Current
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)





description/ordering information

This triple 2-channel CMOS analog multiplexer/demultiplexer is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV4053A handles both analog and digital signals. Each channel permits signals with amplitudes up to 5.5 V (peak) to be transmitted in either direction.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

TA	PACK	(AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	SOIC - D	Tape and reel	SN74LV4053ATDREP	LV4053ATEP
-40 C to 105 C	TSSOP – PW	Tape and reel	SN74LV4053ATPWREP	L4053EP

[‡]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

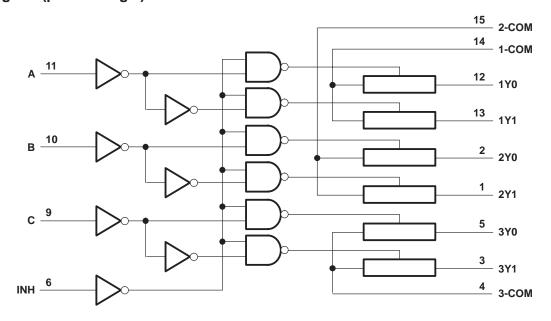


SCLS503C - MAY 2003 - REVISED MAY 2004

FUNCTION TABLE

	INP	UTS		ON OUANINE O
INH	С	В	Α	ON CHANNELS
L	L	L	L	1Y0, 2Y0, 3Y0
L	L	L	Н	1Y1, 2Y0, 3Y0
L	L	Н	L	1Y0, 2Y1, 3Y0
L	L	Н	Н	1Y1, 2Y1, 3Y0
L	Н	L	L	1Y0, 2Y0, 3Y1
L	Н	L	Н	1Y1, 2Y0, 3Y1
L	Н	Н	L	1Y0, 2Y1, 3Y1
L	Н	Н	Н	1Y1, 2Y1, 3Y1
Н	Χ	Χ	Χ	None

logic diagram (positive logic)



SN74LV4053A-EP TRIPLE 2-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS503C - MAY 2003 - REVISED MAY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 7.0 V
Switch I/O voltage range, V _{IO} (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
I/O diode current, I _{IOK} (V _{IO} < 0)	–50 mA
Switch through current, $I_T (V_{IO} = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	
PW package	108°C/W
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2‡	5.5	V	
		V _{CC} = 2 V	1.5			
.,	High lavel in a trueltane anatural in a sta	V _{CC} = 2.3 V to 2.7 V	V _{CC} ×0.7		V	
V_{IH}	High-level input voltage, control inputs	V _{CC} = 3 V to 3.6 V	V _{CC} ×0.7		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$			
		V _{CC} = 2 V		0.5		
\/	Low level input voltage, control inputs	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V	
VIL	Low-level input voltage, control inputs	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$	<u> </u>	
٧ _I	Control input voltage		0	5.5	V	
V _{IO}	Input/output voltage		0	VCC	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V	
		V _{CC} = 4.5 V to 5.5 V		20		
TA	Operating free-air temperature		-40	105	°C	

[‡] With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.



^{2.} This value is limited to 5.5 V maximum.

^{3.} The package thermal impedance is calculated in accordance with JESD 51-7.

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN74LV4053A-EP TRIPLE 2-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS503C - MAY 2003 - REVISED MAY 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST		TA	= 25°C	;			
	PARAMETER	CONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	UNIT
	On atota audiah	1 0 mA V V m OND	2.3 V		41	180		225	
ron	On-state switch resistance	$I_T = 2 \text{ mA}, V_I = V_{CC} \text{ or GND},$ $V_{INH} = V_{II}, \text{ (see Figure 1)}$	3 V		30	150		190	Ω
		HVII IE) (*** 3* *)	4.5 V		23	75		100	
		L 2 m 4 1/2 1/2 2 to CND	2.3 V		139	500		600	
ron(p)	Peak on-state resistance	$I_T = 2 \text{ mA}, V_I = V_{CC} \text{ to GND},$ $V_{INH} = V_{IL}$	3 V		63	180		225	Ω
		- HVIT - FIE	4.5 V		35	100		125	
	Difference in on-state		2.3 V		2	30		40	
Δr_{on}	resistance between	VINII = VII			1.6	20		30	Ω
	switches				1.3	15		20	
lį	Control input current	V _I = 5.5 V or GND	0 to 5.5 V			±0.1		±1	μΑ
IS(off)	Off-state switch leakage current	$V_I = V_{CC}$ and $V_O = GND$, or $V_I = GND$ and $V_O = V_{CC}$, $V_{INH} = V_{IH}$, (see Figure 2)	5.5 V			±0.1		±1	μА
IS(on)	On-state switch leakage current	V _I = V _{CC} or GND, V _{INH} = V _{IH} (see Figure 3)	5.5 V			±0.1		±1	μΑ
ICC	Supply current	$V_I = V_{CC}$ or GND	5.5 V					20	μΑ
C _{IC}	Control input capacitance				2				pF
C _{IS}	Common terminal capacitance				8.2				pF
COS	Switch terminal capacitance				5.6			_	pF
C _F	Feedthrough capacitance				0.5				pF

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

DAD	AMETER	FROM	то	TEST	T	λ = 25°C	;	MAIN	MAN	
PAR	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C _L = 15 pF, (see Figure 4)		2.5	10		16	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn	$C_L = 15 \text{ pF},$ (see Figure 5)		7.6	18		23	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn	$C_L = 15 \text{ pF},$ (see Figure 5)		7.7	18		23	ns
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C _L = 50 pF, (see Figure 4)		4.4	12		18	ns
tPZH tPZL	Enable delay time	INH	COM or Yn	$C_L = 50 \text{ pF},$ (see Figure 5)		8.8	28		35	ns
t _{PHZ}	Disable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		11.7	28		35	ns



SN74LV4053A-EP TRIPLE 2-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER

SCLS503C - MAY 2003 - REVISED MAY 2004

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

DAG	AMETER	FROM	то	TEST	Τμ	λ = 25°C	;	BAINI	MAY	LINUT
PAR	RAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM	$C_L = 15 pF,$ (see Figure 4)		1.6	6		10	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn	C _L = 15 pF, (see Figure 5)		5.3	12		15	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn	C _L = 15 pF, (see Figure 5)		6.1	12		15	ns
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM	C _L = 50 pF, (see Figure 4)		2.9	9		12	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		6.1	20		25	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		8.9	20		25	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted)

DAD	AMETER	FROM	то	TEST	T	λ = 25°C	;	MAINI	MAN	
PAR	AMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP	MAX	MIN	MAX	UNIT
tPLH tPHL	Propagation delay time	COM or Yn	Yn or COM	C _L = 15 pF, (see Figure 4)		0.9	4		7	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn	$C_L = 15 pF,$ (see Figure 5)		3.8	8		10	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn	C _L = 15 pF, (see Figure 5)		4.6	8		10	ns
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM	C _L = 50 pF, (see Figure 4)		1.8	6		8	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		4.3	14		18	ns
tPHZ tPLZ	Disable delay time	INH	COM or Yn	C _L = 50 pF, (see Figure 5)		6.3	14		18	ns

SCLS503C - MAY 2003 - REVISED MAY 2004

analog switch characteristics

DADAMETED	FROM	то	TEST COM	IDITIONS	V	T,	չ = 25°C	;	LINUT			
PARAMETER	(INPUT)	(OUTPUT)	TEST CON	DITIONS	vcc	MIN	TYP	MAX	UNIT			
			1		2.3 V		30					
Frequency response (switch on)	COM or Yn	Yn or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$ (sine	wave)	3 V		35		MHz			
(SWILOTT STT)			(see Note 5 and		4.5 V		50					
			$C_L = 50 \text{ pF},$		2.3 V		-45					
Crosstalk (between any switches)	COM or Yn	Yn or COM	R _L = 600Ω , f_{in} = 1 MHz (sine wave) (see Note 6 and Figure 7)		3 V		-45		dB			
(comesn any contents)					4.5 V		-45					
Crosstalk			$C_L = 50 \text{ pF},$ $R_L = 600 \Omega,$ $f_{in} = 1 \text{ MHz (square wave)}$		2.3 V		20					
(control input to signal	INH	COM or Yn			3 V		35		mV			
output)			(see Figure 8)	4.5 V		65						
			C _L = 50 pF,		2.3 V		-45					
Feedthrough attenuation (switch off)	COM or Yn	Yn or COM	$R_L = 600 \Omega$, $f_{in} = 1 MHz$		3 V		-45		dB			
(Simon on)			(see Note 6 and	Figure 9)	4.5 V		-45					
			C _L = 50 pF,	V _I = 2 V _{p-p}	2.3 V		0.1					
Sine-wave distortion	COM or Yn			Yn or COM	Yn or COM $f_{in} = 1 \text{ kHz}$	$R_L = 10 \text{ k}\Omega$, $f_{\text{in}} = 1 \text{ kHz}$	V _I = 2.5 V _{p-p}	3 V		0.1		%
			(sine wave) (see Figure 10)	V _I = 4 V _{p-p}	4.5 V		0.1					

NOTES: 5. Adjust f_{in} voltage to obtain 0-dBm output. Increase f_{in} frequency until dB meter reads –3 dB.

6. Adjust fin voltage to obtain 0-dBm input.

operating characteristics, V_{CC} = 3.3 V, T_A = 25°C

	PARAMETER	TEST CON	TYP	UNIT	
C _{pd}	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	5.3	pF

PARAMETER MEASUREMENT INFORMATION

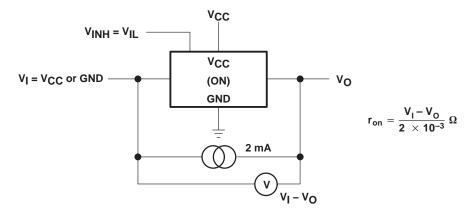
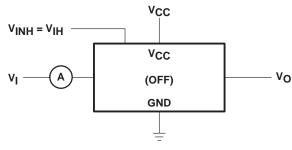


Figure 1. On-State Resistance Test Circuit





Condition 1: $V_I = 0$, $V_O = V_{CC}$ Condition 2: $V_I = V_{CC}$, $V_O = 0$

Figure 2. Off-State Switch Leakage-Current Test Circuit

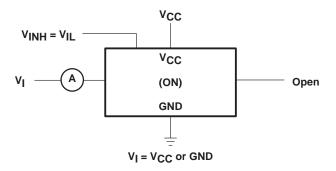


Figure 3. On-State Switch Leakage-Current Test Circuit

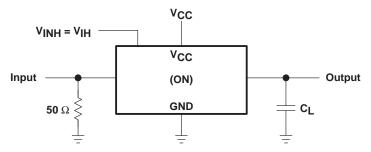
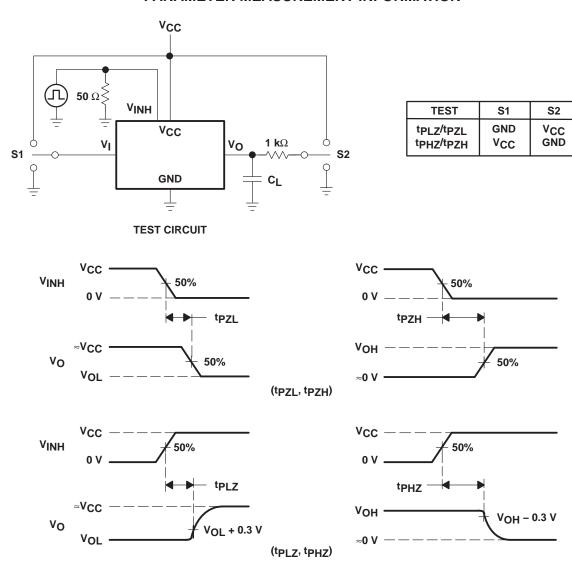


Figure 4. Propagation Delay Time, Signal Input to Signal Output



VOLTAGE WAVEFORMS

Figure 5. Switching Time (t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}), Control to Signal Output

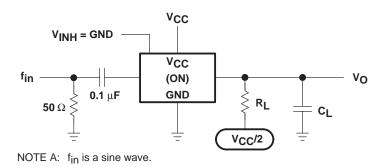


Figure 6. Frequency Response (Switch On)



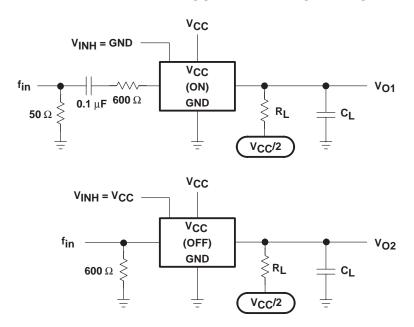


Figure 7. Crosstalk Between Any Two Switches

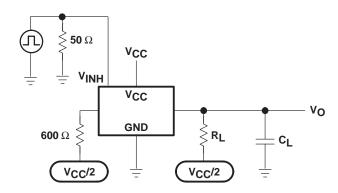


Figure 8. Crosstalk Between Control Input and Switch Output

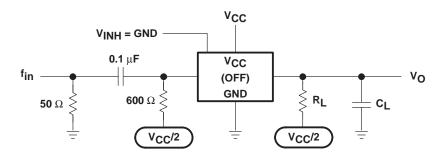


Figure 9. Feedthrough Attenuation (Switch Off)

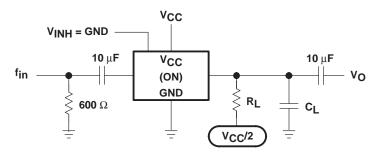


Figure 10. Sine-Wave Distortion





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV4053ATDREP	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4053ATPWREP	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03666-01XE	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03666-01YE	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV4053A-EP:

Automotive: SN74LV4053A-Q1

NOTE: Qualified Version Definitions:

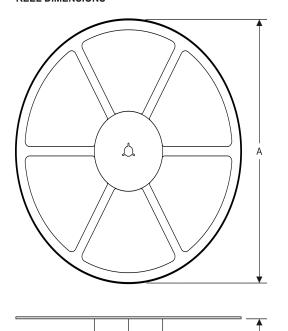
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

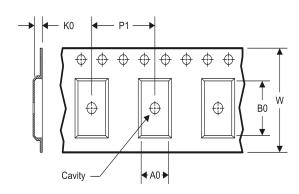
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV4053ATDREP	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV4053ATPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV4053ATDREP	SOIC	D	16	2500	333.2	345.9	28.6
SN74LV4053ATPWREP	TSSOP	PW	16	2000	367.0	367.0	35.0

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